Stackpole Electronics, Inc.

General Purpose Metal Oxide Resistor

Resistive Product Solution

Features:

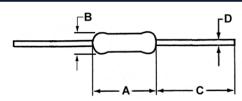
- Lower-cost alternative to carbon comps and wirewounds
- Coating meets UL 94V-0
- Meets solvent test of Mil Standard 202, Method 215
- Cut and formed product is available on select sizes contact Stackpole for details
- Higher or lower resistance values may be possible contact Stackpole
- Flameproof
- RoHS compliant, lead free and halogen free



	Electrical Specifications								
Type / Code	Power Rating	Maximum Working	Maximum Overload	Dielectric Withstanding	I Ohmi		Range (Ω) and Tolerance		
	(W) @ 70°C	Voltage (V) ⁽¹⁾	Voltage (V)	Voltage (V)	"",	1%	2%	5%	
RSF12	0.5	250	400	350	± 200	0.1 - 150K	0.1 - 75K	0.1 - 1M	
RSF1	1	350	600	600	± 200	0.1 - 100K 0.1 - 1M		0.1 - 1M	
RSF2	2	350	600	600	± 200	0.1 - 120K		0.1 - 1M	
RSF3	3	800	1000	750	± 200	0.1 - 470K	0.1 - 560K	0.1 - 1M	
RSF5	5	1000	1000	750	± 200	0.1 - 470K	0.1 - 560K	0.1 - 1M	
RSMF12	0.5	250	400	350	± 200	0.1 - 46.4K	0.1 - 47K	0.1 - 470K	
RSMF1	1	350	600	500	± 200	0.1 -	75K	0.1 - 470K	
RSMF2	2	350	600	500	± 200	0.1 -	100K	0.1 - 470K	
RSMF3	3	500	800	600	± 200	0.1 - 118K	0.1 - 120K	0.1 - 470K	
RSMF5	5	1000	1000	750	± 200	0.1 - 470K	0.1 - 560K	0.1 - 1M	

⁽¹⁾ Lesser of √P*R or maximum working voltage

Mechanical Specifications

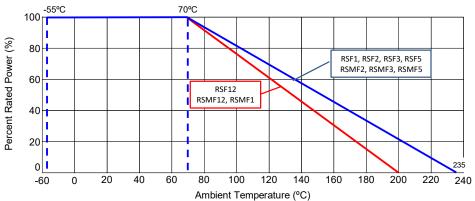


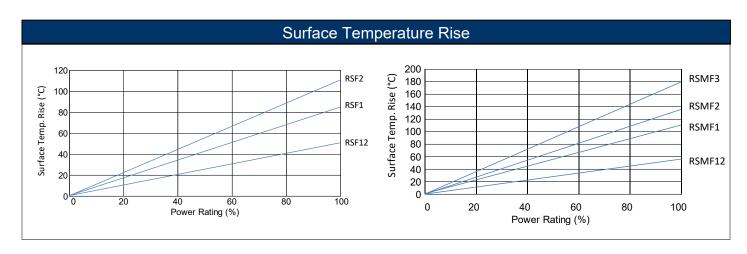
Type / Code	A	В	С	D	Lead-Tape	Unit
Type / Code	Body Length	Body Diameter	Lead Length (Bulk)	Lead Diameter	Specification	Offic
RSF12	0.35 ± 0.04	0.13 ± 0.03	1.10 ± 0.12	0.03 ± 0.003	0.250	inches
ROFIZ	9.00 ± 1.00	3.20 ± 0.80	28.00 ± 3.00	0.70 ± 0.08	6.35	mm
RSF1	0.43 ± 0.06	0.18 ± 0.04	1.10 ± 0.20	0.03 ± 0.002	0.250	inches
Nori	11.00 ± 1.50	4.50 ± 1.00	28.00 ± 5.00	0.80 ± 0.05	6.35	mm
RSF2	0.59 ± 0.06	0.22 ± 0.04	1.18 ± 0.20	0.03 ± 0.004	0.250	inches
NOFZ	15.00 ± 1.50	5.50 ± 1.00	30.00 ± 5.00	0.75 ± 0.10	6.35	mm
RSF3	0.69 ± 0.04	0.24 ± 0.02	1.38 ± 0.12	0.03 ± 0.002	0.250	inches
Rora	17.50 ± 1.00	6.00 ± 0.50	35.00 ± 3.00	0.80 ± 0.05	6.35	mm
RSF5	0.96 ± 0.04	0.31 ± 0.02	1.38 ± 0.12	0.03 ± 0.002	0.250	inches
Koro	24.50 ± 1.00	8.00 ± 0.50	35.00 ± 3.00	0.80 ± 0.05	6.35	mm
RSMF12	0.24 ± 0.03	0.09 ± 0.01	1.10 ± 0.12	0.02 ± 0.003	0.250	inches
NOWII 12	6.00 ± 0.80	2.30 ± 0.30	28.00 ± 3.00	0.55 ± 0.07	6.35	mm
RSMF1	0.35 ± 0.04	0.13 ± 0.03	1.10 ± 0.12	0.03 ± 0.003	0.250	inches
INSIVII I	9.00 ± 1.00	3.20 ± 0.80	28.00 ± 3.00	0.70 ± 0.08	6.35	mm
RSMF2	0.43 ± 0.06	0.18 ± 0.04	1.18 ± 0.20	0.03 ± 0.002	0.250	inches
INDIVII Z	11.00 ± 1.50	4.50 ± 1.00	30.00 ± 5.00	0.80 ± 0.05	6.35	mm
RSMF3	0.59 ± 0.06	0.22 ± 0.04	1.18 ± 0.20	0.03 ± 0.004	0.250	inches
NOIVIFO	15.00 ± 1.50	5.50 ± 1.00	30.00 ± 5.00	0.75 ± 0.10	6.35	mm
RSMF5	0.69 ± 0.04	0.24 ± 0.02	1.38 ± 0.08	0.03 ± 0.002	0.250	inches
NOIVIED	17.50 ± 1.00	6.00 ± 0.50	35.00 ± 2.00	0.80 ± 0.05	6.35	mm

Performance Characteristics							
Test	Test Method	Test Specification	Typical Results				
Insulation Resistance	JIS C5201-1, IEC60115-1, 4.6	≥ 1G Ω	≥ 1G Ω				
Voltage Proof	JIS C5201-1, IEC60115-1, 4.7	\leq ± (0.5% + 0.05 Ω) No mechanical damage	< ± 0.25%				
Short Time Overload	JIS C5201-1, IEC60115-1, 4.13	≤± (0.75% + 0.05 Ω)	< ± 0.1%				
Resistance to Solder Heat	JIS C5201-1, IEC60115-1, 4.18	$\leq \pm (2.0\% + 0.05 \Omega)$	< ± 1.0%				
Endurance at 70°C	JIS C5201-1, IEC60115-1, 4.25.1	≤± (5.0% + 0.05 Ω)	< ± 2.0%				
Robustness of Terminations	JIS C5201-1, IEC60115-1, 4.16	$\leq \pm (1.0\% + 0.05 \Omega)$	< ± 0.10%				
Damp Heat (Steady state)	JIS C5201-1, IEC60115-1, 4.24	≤± (5% + 0.05 Ω)	< ± 1.5%				
Rapid Change of Temperature	JIS C5201-1, IEC60115-1, 4.19	≤± (1% + 0.05 Ω)	< ± 0.2%				
Resistance to Solvents	JIS C5201-1, IEC60115-1, 4.29	No damage to component or removal of marking	Pass				
Intermittent Overload	JIS C5201-1, IEC60115-1, 4.39	≤± (2% + 0.05 Ω)	< ± 0.3%				
Accidental Overload (Flame resistance)	JIS C5201-1, IEC60115-1, 4.26	No flaming of gauze	Pass				

Operating temperature range is -55°C to +200°C (RSF12, RSMF12, RSMF1) -55°C to +235°C (all others)

Power Derating Curve:





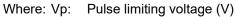
Repetitive Pulse Information:

If repetitive pulses are applied to resistors, pulse wave form must be less than "pulse limiting voltage", "pulse limiting current" or "pulse limiting wattage" calculated by the formula below.

$$Vp = K\sqrt{P \times R \times T/t}$$

$$Ip = K\sqrt{P/R \times T/t}$$

$$Pp = K^2 x P x T/t$$



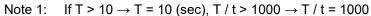
lp: Pulse limiting current (A)
Pp: Pulse limiting wattage (W)

P: Power rating (W)

R: Nominal resistance (ohm)
T: Repetitive period (sec)
t: Pulse duration (sec)

K: Coefficient: 0.8

[Vr: Rated Voltage (V), Ir: Rated Current (A)]



Note 2: If T > 10 and T / t > 1000, "Pulse Limiting power (Single pulse) is applied

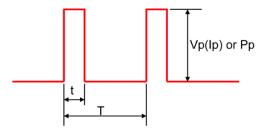
Note 3: If Vp < Vr (Ip < Ir or Pp < P), Vr (Ir, P) is Vp (Ip, Pp)

Note 4: Pulse limiting voltage (current, wattage) is applied at less than rated ambient temperature. If ambient temperature is more than the rated temperature (70 °C), decrease power rating according to "Power Derating Curve"

Note 5: Assure sufficient margin for use period and conditions for "pulse limiting voltage"

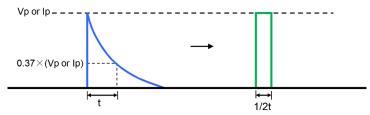
Note 6: If the pulse waveform is not square wave, judge after transform the waveform into square

wave according to the "Waveform Transformation to Square Wave".

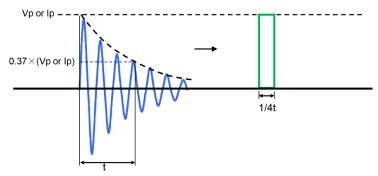


Waveform Transformation to Square Wave

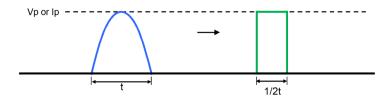
1. Discharge curve wave with time constant "t" → Square wave



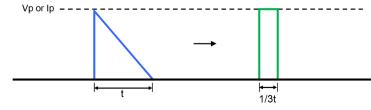
2. Damping oscillation wave with time constant of envelope "t" → Square wave



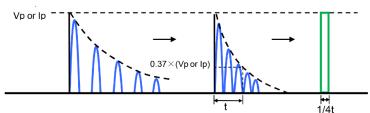
3. Half-wave rectification wave → Square wave



4. Triangular wave → Square wave



5. Special wave → Square wave



Recommended Solder Profile

This information is intended as a reference for solder profiles for Stackpole resistive components. These profiles should be compatible with most soldering processes. These are only recommendations. Actual numbers will depend on board density, geometry, packages used, etc., especially those cells labeled with "*".

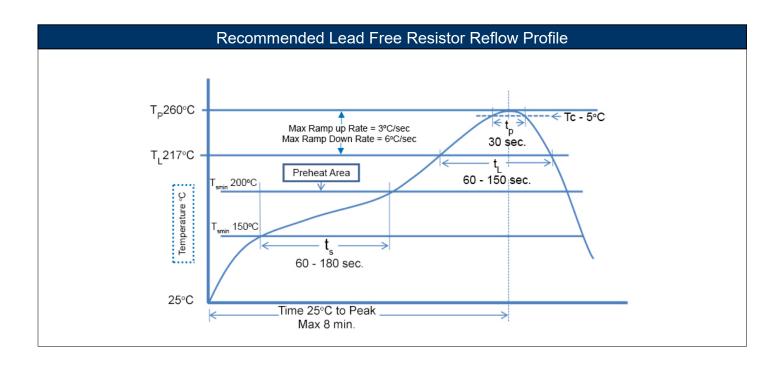
100% Matte Tin / RoHS Compliant Terminations

Soldering iron recommended temperatures: 330°C to 350°C with minimum duration. Maximum number of reflow cycles: 3.

Wave Soldering						
Description Maximum Recommended Minimum						
Preheat Time	80 seconds	70 seconds	60 seconds			
Temperature Diff.	140°C	120°C	100°C			
Solder Temp.	260°C	250°C	240°C			
Dwell Time at Max.	10 seconds	5 seconds	*			
Ramp DN (°C/sec)	N/A	N/A	N/A			

Temperature Diff. = Defference between final preheat stage and soldering stage.

Convection IR Reflow					
Description Maximum Recommended Minimum					
Ramp Up (°C/sec)	3°C/sec	2°C/sec	*		
Dwell Time > 217°C	150 seconds	90 seconds	60 seconds		
Solder Temp.	260°C	245°C	*		
Dwell Time at Max.	30 seconds	15 seconds	10 seconds		
Ramp DN (°C/sec)	6°C/sec	3°C/sec	*		



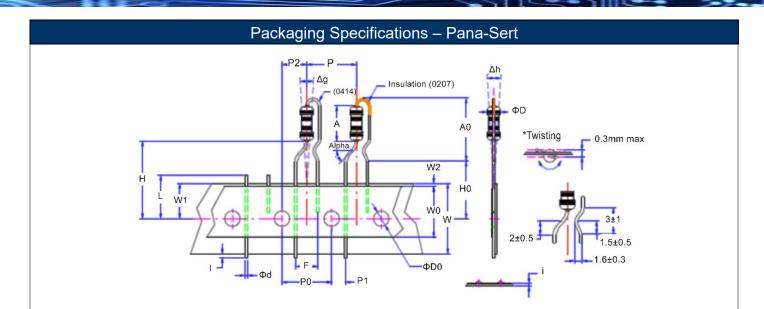
Resistive Product Solutions

Type / Code	A max ⁽¹⁾	B max	С	D ⁽²⁾	Tape	Unit
RSF12	2.736	13.504	0.197 ± 0.020	2.063 ± 0.079	0.250	inches
NOF 12	69.50	343.00	5.00 ± 0.50	52.40 ± 2.00	6.35	mm
RSF1	2.815	13.504	0.197 ± 0.020	2.063 ± 0.079	0.250	inches
KOFT	71.50	343.00	5.00 ± 0.50	52.40 ± 2.00	6.35	mm
RSF2	3.524	13.504	0.394 ± 0.020	2.500 ± 0.079	0.250	inches
NOF2	89.50	343.00	10.00 ± 0.50	63.50 ± 2.00	6.35	mm
RSF3	3.740	12.008	0.394 ± 0.020	2.874 ± 0.079	0.250	inches
ROFS	95.00	305.00	10.00 ± 0.50	73.00 ± 2.00	6.35	mm
RSF5	4.331	12.008	0.394 ± 0.020	3.465 ± 0.079	0.250	inches
1101 3	110.00	305.00	10.00 ± 0.50	88.00 ± 2.00	6.35	mm
Type / Code	A max ⁻⁽¹⁾	B max	С	D ⁽²⁾	Tape	Unit
RSMF12	2.618	13.504	0.197 ± 0.020	2.063 ± 0.079	0.250	inches
NOIVIF 12	66.50	343.00	5.00 ± 0.50	52.40 ± 2.00	6.35	mm
RSMF1	2.736	13.504	0.197 ± 0.020	2.063 ± 0.079	0.250	inches
ROWE	69.50	343.00	5.00 ± 0.50	52.40 ± 2.00	6.35	mm
RSMF2	2.815	13.504	0.197 ± 0.020	2.063 ± 0.079	0.250	inches
ROWIFZ	71.50	343.00	5.00 ± 0.50	52.40 ± 2.00	6.35	mm
RSMF3	3.524	13.504	0.394 ± 0.020	2.500 ± 0.079	0.250	inches
NOIVIFO	89.50	343.00	10.00 ± 0.50	63.50 ± 2.00	6.35	mm
RSMF5	3.740	12.008	0.394 ± 0.020	2.874 ± 0.079	0.250	inches
KONIES	95.00	305.00	10.00 ± 0.50	73.00 ± 2.00	6.35	mm

Dimension "E": This is a non-critical dimension that does not have a tolerance in the standard. Range of diameters is from 0.547 inches (13.90 mm) to 1.500 inches (38.10 mm).

- (1) Reference value only. The "A" dimension shall be governed by the overall length of the taped component. The distance between flanges shall be 0.059 inches (1.50 mm) to 0.315 (8.00 mm) greater than the overall component.
- (2) The given dimension "D" expresses the standard width spacing. A 26 mm narrow spacing is available as option "N" packaging code.

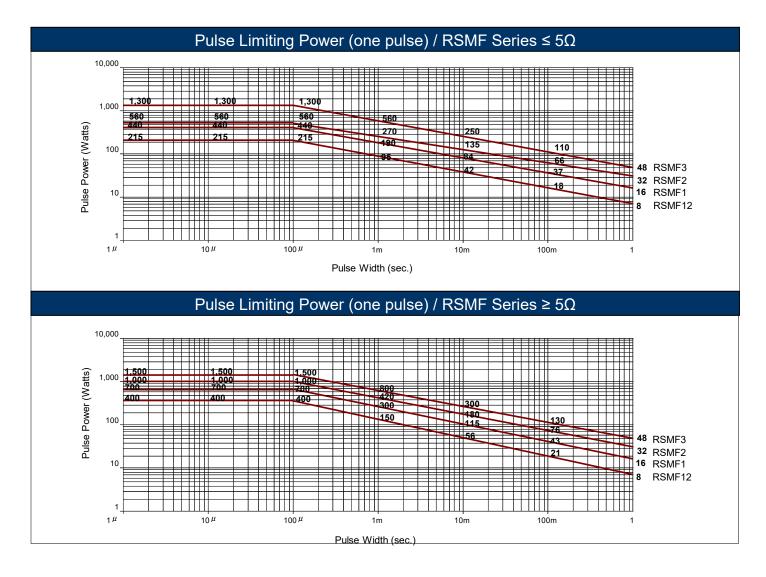
Resistive Product Solutions



Symbol	Description	PRSM12	PRSF1 / PRSM2		
ØD	Body diameter	0.157 max. 0.217 max. 4.00 max. 5.50 max.			
A	Body length	0.394 max.	0.492 max.		
, ,	200, iong	10.00 max.	12.50 max.		
A0	Mounting height	0.571 max. 0.709 max.			
	gg	14.50 max.	18.00 max.		
Ød	Lead diameter	ameter 0.028 ± 0.004 0.028 ± 0.0			
	2000 0.0	0.70 ± 0.10	0.70 ± 0.10		
Р	Component pitch	0.500 =			
·	Сеттреттетт рист	12.70 :			
P0	Feed hole pitch	0.500 =			
. 0	r odd neid piteri	12.70 :			
P1	Feed hole center to lead	0.152 :			
	1 dea fiele deficer to load		± 0.50		
P2	Feed hole center to body	0.250 :			
	r dea nele contente beay	6.35 ± 0.40			
F	Lead-lead distance	Lead-lead distance 0.200 +0.24 / -0.008			
•	Load load distance	5.08 +0.60 / -0.20			
Alpha	Performing angle	45° max			
Δh	Commonant alignment	0.000 ± 0.079			
ΔΠ	Component alignment	0.00 =	± 2.00		
٨α	Component alignment	0.000 :	± 0.118		
Δg	Component alignment	0.00 :	0.00 ± 3.00		
W	Tape width	0.709 -	+0.039 / -0.031		
VV	rape width	18.00 -	+1.00 / -0.80		
WO	Hold down tape width	0.492 r	nin.		
VVU	Holu down tape width	12.50 r	min.		
W1	Hole position	0.354 :	± 0.020		
VVI	Hole position	9.00 =	± 0.50		
W2	Hold down tape position		+0 / -0.059		
VVZ	I loid down tape position	2.00 -	2.00 +0 / -1.50		

Resistive Product Solutions

Packaging Specifications – Pana-Sert (cont.)							
Symbol	Description	PRSM12	PRSF1 / PRSM2				
Н	Distance to tape center	Distance to tape center 0.748 ± 0.039 19.00 ± 1.00					
HO	Lead wire clinch height	0.630 ± 0.020 16.00 ± 0.50					
I	Lead wire portrait	0.039 max. 1.00 max.					
ØD0	Feed hole diamenter	0.157 ± 0.008 4.00 ± 0.20					
i	Total tape thickness	0.028 max. 0.70 max.					
L	Length of shipped lead	0.433 max. 11.00 max.					



Stackpole Electronics, Inc.

General Purpose Metal Oxide Resistor

Resistive Product Solutions

RoHS Compliance

Stackpole Electronics has joined the worldwide effort to reduce the amount of lead in electronic components and to meet the various regulatory requirements now prevalent, such as the European Union's directive regarding "Restrictions on Hazardous Substances" (RoHS 3). As part of this ongoing program, we periodically update this document with the status regarding the availability of our compliant components. All our standard part numbers are compliant to EU Directive 2011/65/EU of the European Parliament as amended by Directive (EU) 2015/863/EU as regards the list of restricted substances.

	RoHS Compliance Status							
Standard Product Series	Description	Package / Termination Type	Standard Series RoHS Compliant	Lead-Free Termination Composition	Lead-Free Mfg. Effective Date (Std Product Series)	Lead-Free Effective Date Code (YY/WW)		
RSF	General Purpose Metal Oxide Leaded Resistor	Axial	YES	99.3/0.7 Sn/Cu 100% Matte Sn	Apr-05 (Japan) Jan-04 (Taiwan, China)	05/14 04/01		
RSMF	Mini-Metal Oxide Leaded Resistor	Axial	YES	99.3/0.7 Sn/Cu 100% Matte Sn	Apr-05 (Japan) Jan-04 (Taiwan, China)	05/14 04/01		

"Conflict Metals" Commitment

We at Stackpole Electronics, Inc. are joined with our industry in opposing the use of metals mined in the "conflict region" of the Eastern Democratic Republic of the Congo (DRC) in our products. Recognizing that the supply chain for metals used in the electronics industry is very complex, we work closely with our own suppliers to verify to the extent possible that the materials and products we supply do not contain metals sourced from this conflict region. As such, we are in compliance with the requirements of Dodd-Frank Act regarding Conflict Minerals.

Compliance to "REACH"

We certify that all passive components supplied by Stackpole Electronics, Inc. are SVHC (Substances of Very High Concern) free and compliant with the requirements of EU Directive 1907/2006/EC, "The Registration, Evaluation, Authorization and Restriction of Chemicals", otherwise referred to as REACH. Contact us for complete list of REACH Substance Candidate List.

Environmental Policy

It is the policy of Stackpole Electronics, Inc. (SEI) to protect the environment in all localities in which we operate. We continually strive to improve our effect on the environment. We observe all applicable laws and regulations regarding the protection of our environment and all requests related to the environment to which we have agreed. We are committed to the prevention of all forms of pollution.

